

Number of Components: Single

Mix Ratio By Weight: N/A

Specific Gravity: 1.78

Part A

Part B

Pot Life: 15 Days

Shelf Life: 1 year refrigerated

Note: Container(s) should be kept closed when not in use. For filled systems, mix contents of container thoroughly.

**Please see Applications Note available on our website.*

Minimum Bond Line Cure Schedule*:

150°C 30 Minutes

120°C 1 Hour

Product Description:

EPO-TEK[®] H62 is a single component, electrically insulating, and thermally conductive epoxy adhesive. It may be used for heat-sinking semiconductor, hybrids, or electronic circuits.

EPO-TEK[®] H62 Advantages & Application Notes:

- Black and opaque appearance; it can block out light in opto-electronic devices.
- Semiconductor encapsulant for COB packaged die. It may be used as a glob top DAM around the chip.
- SMD “staking” material or Surface Mount Adhesive (SMA). The SMA may be used for double-sided PCB bonding of components; staking caps and resistors to ceramic or hybrid circuits. High viscosity adhesive paste has enough wet “green strength” to hold SMD’s to the PCB prior to cure.
- Alternatives are available in different viscosity ranges and colors; contact techserv@epotek.com for your best recommendation.
- Excellent adhesion to ferrous and non-ferrous metals, glass, ceramics, PCB, and most plastics.
- Thixotropic paste appearance makes it capable of syringe dispensing techniques, stencil or screen printing, or hand applications by brush or spatula.

Typical Properties: *(To be used as a guide only, not as a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results; Cure condition: 150°C/1 hour; * denotes test on lot acceptance basis)*

Physical Properties:	
*Color: Black, Opaque	Weight Loss:
*Consistency: Smooth thixotropic paste	@ 200°C: 0.31%
*Viscosity (@ 10 RPM/23°C): 17,000 – 27,000 cPs	@ 250°C: 0.42%
Thixotropic Index: 1.89	@ 300°C: 0.62%
*Glass Transition Temp.(Tg): ≥ 110°C (Dynamic Cure 20—200°C /ISO 25 Min; Ramp -10—200°C @ 20°C/Min)	Operating Temp:
Coefficient of Thermal Expansion (CTE):	Continuous: - 55°C to 275°C
Below Tg: 48×10^{-6} in/in/°C	Intermittent: - 55°C to 375°C
Above Tg: 119×10^{-6} in/in/°C	Storage Modulus @ 23°C: 656,630 psi
Shore D Hardness: 80	Ions: Cl ⁻ 55 ppm
Lap Shear Strength @ 23°C: 600 psi	Na ⁺ 136 ppm
Die Shear Strength @ 23°C: ≥ 15 Kg / 5,100 psi	NH ₄ ⁺ 96 ppm
Degradation Temp. (TGA): 436°C	K ⁺ 28 ppm
	*Particle Size: ≤ 50 Microns
Optical Properties:	
Index of Refraction @ 23°C: N/A	Spectral Transmission @ 23°C: < 1% @ 300-2500 nm
Electrical & Thermal Properties:	
Thermal Conductivity: 0.50 W/mK	Volume Resistivity @ 23°C: ≥ 2×10^{13} Ohm-cm
Dielectric Constant (1KHz): 4.65	Dissipation Factor (1KHz): 0.011

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